CLAIMS

1. A method for manufacturing an electronic device, the method comprising at least:

a step (1) of preparing a structure comprising

an adhesive film provided with a base material layer, an adhesive resin layer (A) provided on a first surface side of the base material layer, and an adhesive resin layer (B) provided on a second surface side of the base material layer and in which an adhesive force is reduced by an external stimulus, in which a storage modulus E' at 125°C of the adhesive resin layer (A) is 0.2×10^6Pa or more and 4.5×10^6Pa or less,

an electronic component attached to the adhesive resin layer (A) of the adhesive film, and

a support substrate attached to the adhesive resin layer (B) of the adhesive film;

a step (2) of sealing the electronic component with a sealing material;

a step (3) of peeling the support substrate from the structure by reducing an adhesive force of the adhesive resin layer (B) by applying an external stimulus; and

a step (4) of peeling the adhesive film from the electronic component, and the adhesive resin layer (A) includes a (meth)acrylic-based adhesive resin.

2. The method for manufacturing an electronic device according to claim 1,

wherein the adhesive resin layer (B) is an adhesive film in which an adhesive force is reduced by heating at a temperature exceeding 150°C, and the step (3) includes heating at a temperature exceeding 150°C.

3. The method for manufacturing an electronic device according to claim 1 or 2,

wherein the adhesive resin layer (B) includes at least one selected from gas generating components and thermally expandable microspheres.

4. The method for manufacturing an electronic device according to any one of claims 1 to 3,

wherein the sealing material is an epoxy resin-based sealing material.